



ES2ABF THRU ES2JBF

Reverse Voltage - 50 to 600 Volts Forward Current 2.0 Ampere

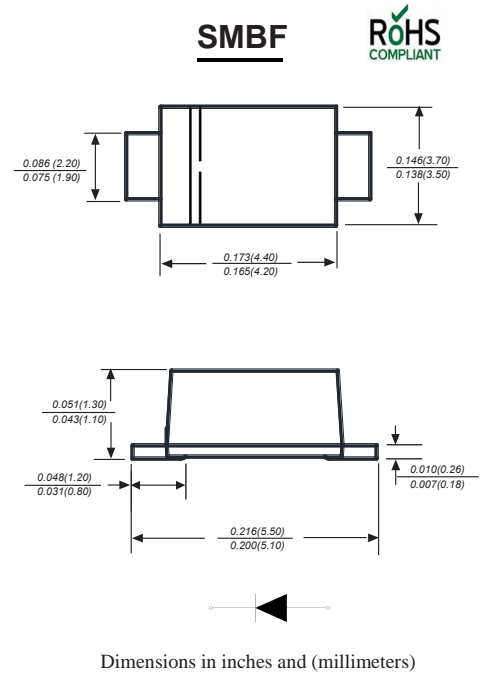
SURFACE MOUNT SUPER FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
 - ◆ 250°C/10 seconds at terminals
 - ◆ Glass passivated chip junction

Mechanical Data

Case : JEDEC SMBF Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.002 ounce, 0.055 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ES2ABF	ES2BBF	ES2CBF	ES2DBF	ES2EBF	ES2GBF	ES2JBF	UNITS
		MDD E2AB	MDD E2BB	MDD E2CB	MDD E2DB	MDD E2EB	MDD E2GB	MDD E2JB	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	V_{DC}	50	100	150	200	300	400	600	V
Maximum average forward rectified current at $T_L=55^\circ\text{C}$	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Maximum instantaneous forward voltage at 3.0A	V_F	1			1.25		1.70		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R	5.0			100.0				μA
Maximum reverse recovery time (NOTE 1)	t_{rr}	35							ns
Typical junction capacitance (NOTE 2)	C_J	45.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	65.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

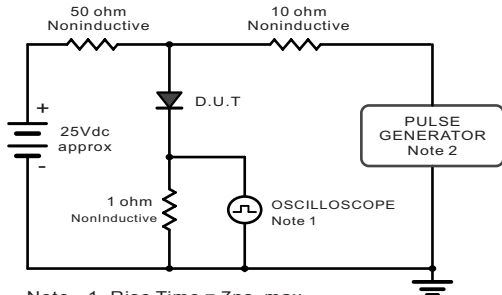
Note: 1. Reverse recovery condition $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas



ES2ABF THRU ES2JBF

Reverse Voltage - 50 to 600 Volts Forward Current - 2.0 Ampere

Ratings And Characteristic Curves



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

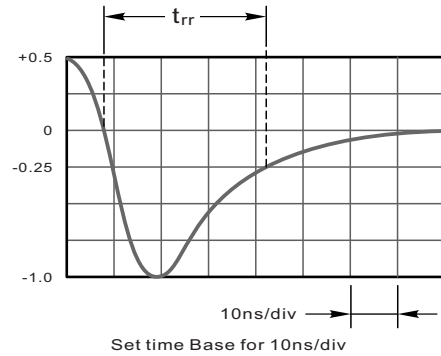


Fig.2 Maximum Average Forward Current Rating

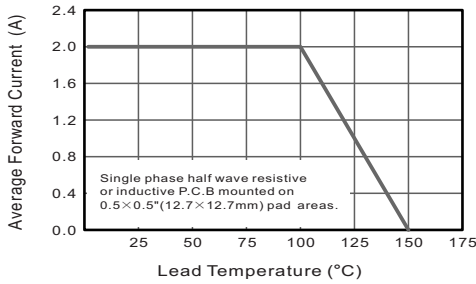


Fig.3 Typical Reverse Characteristics

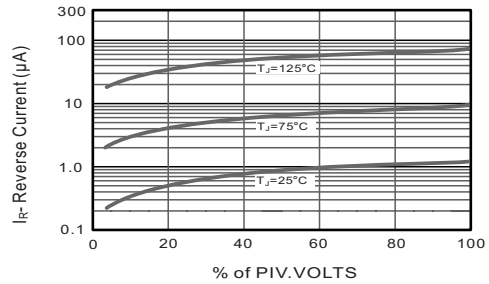


Fig.4 Typical Forward Characteristics

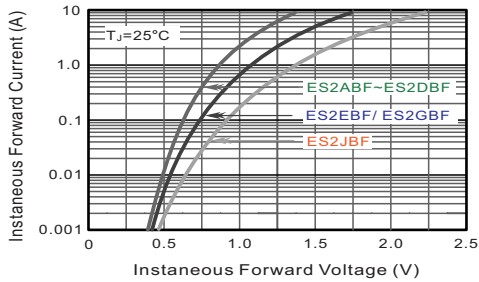


Fig.5 Typical Junction Capacitance

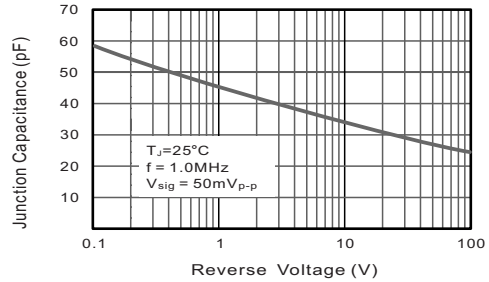
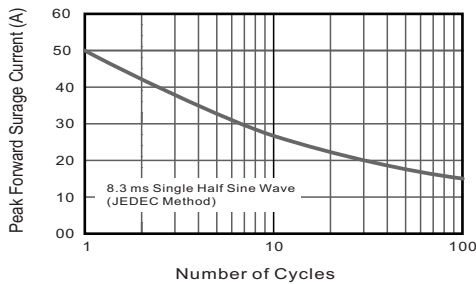


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



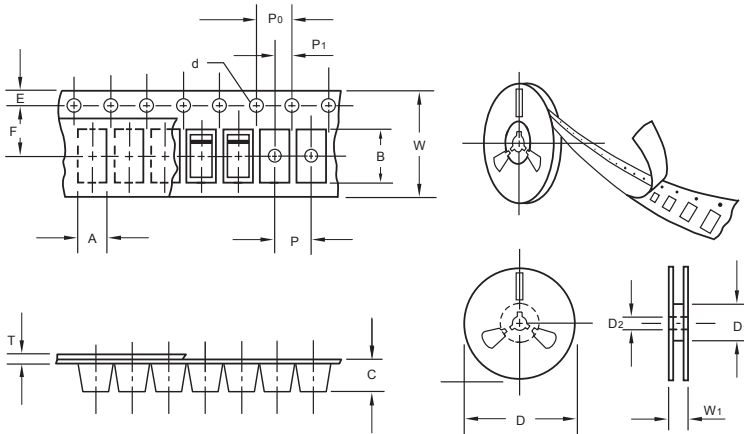
The curve above is for reference only.



ES2ABF THRU ES2JBF

Reverse Voltage - 50 to 600 Volts Forward Current - 2.0 Ampere

Packing information



unit:mm

Item	Symbol	Tolerance	SMBF
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.61
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMBF	13"	5,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.54	0.100
B	1.8	0.071
C	4.8	0.189
D	3.0	0.118
E	6.6	0.260